

/ Descriptions

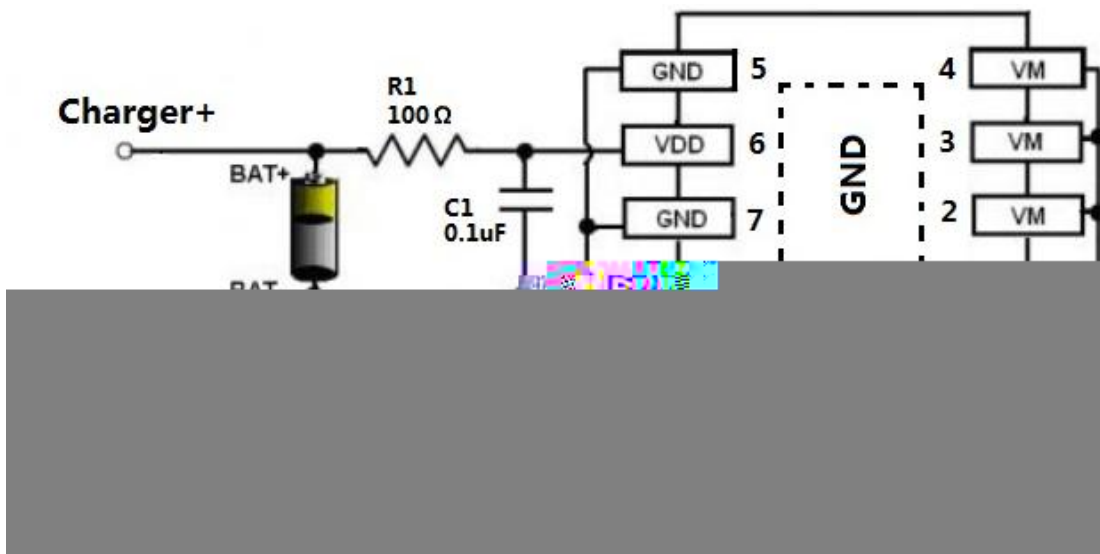
BRCL3120SE / BRCL3120SE
MOSFET
BRCL3120SE

/ Features

- ◆ 25m MOSFET
- ◆
- ◆ 2
- ◆ 0V
- ◆ 5.6uA 3uA; ROHS
- ◆

/ Applications

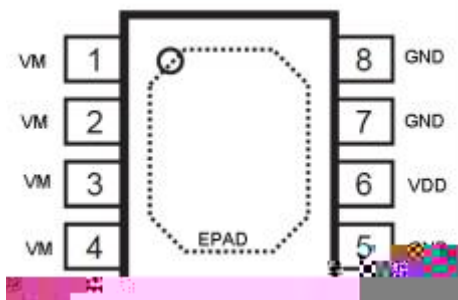
/ Typical Application



- 1.
- 2.



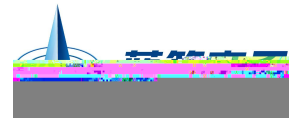
/ Pinning



1 2 3 4	VM	GND
5 7 8	GND	
6	VDD	
9	EPAD	EPAD BRCL3120SE ,GND

/ Marking

See Marking Instructions.

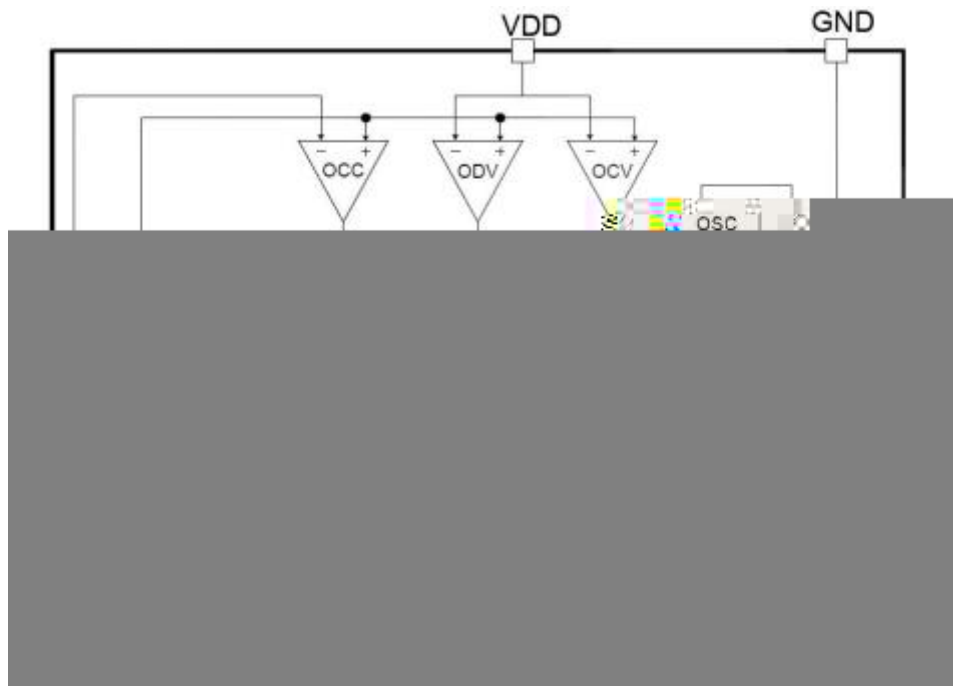
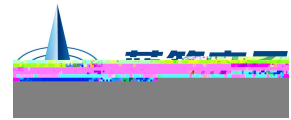


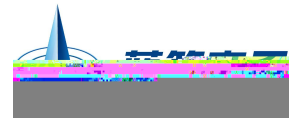
/ Absolute Maximum Ratings(Ta=25)

VDD	V _{IN}	-0.3 to +6.0	V
VM	V _{VM}	-6.0 to +10	V
	T _J	125	°C
	T _L	300	°C
	T _{opr}	-40 to +85	°C
	T _{stg}	-55 to +150	°C
	ESD	2000	V

/ Electrical Characteristics(Ta=25)

	V _{CU}		4.25	4.30	4.35	V
	V _{CL}		4.05	4.10	4.15	V
	V _{DL}		2.30	2.40	2.50	V
	V _{DR}		2.90	3.00	3.10	V
	V _{CHA}			-0.12		V
1	I _{IOV1}	V _{dd} =3.5V		6		A
	I _{SHORT}	V _{dd} =3.5V		25		A
	I _{OPe}	V _{dd} =3.5V, V _M =0V		5	12	μA
	I _{PDN}	V _{dd} =2V V _M floating		3	12	μA
	R _{DS}	V _{dd} =3.6V, I _{VM} =1A		25		m
				120		°C
				100		°C
	T _{CU}	V _{DD} =3.6V~4.4V		130	200	ms
	T _{DL}	V _{DD} =3.6V~2.0V		40	60	ms
1	T _{IOV1}	V _{DD} =3.6V		8.0		ms
	T _{SHORT}	V _{DD} =3.6V		32		μS





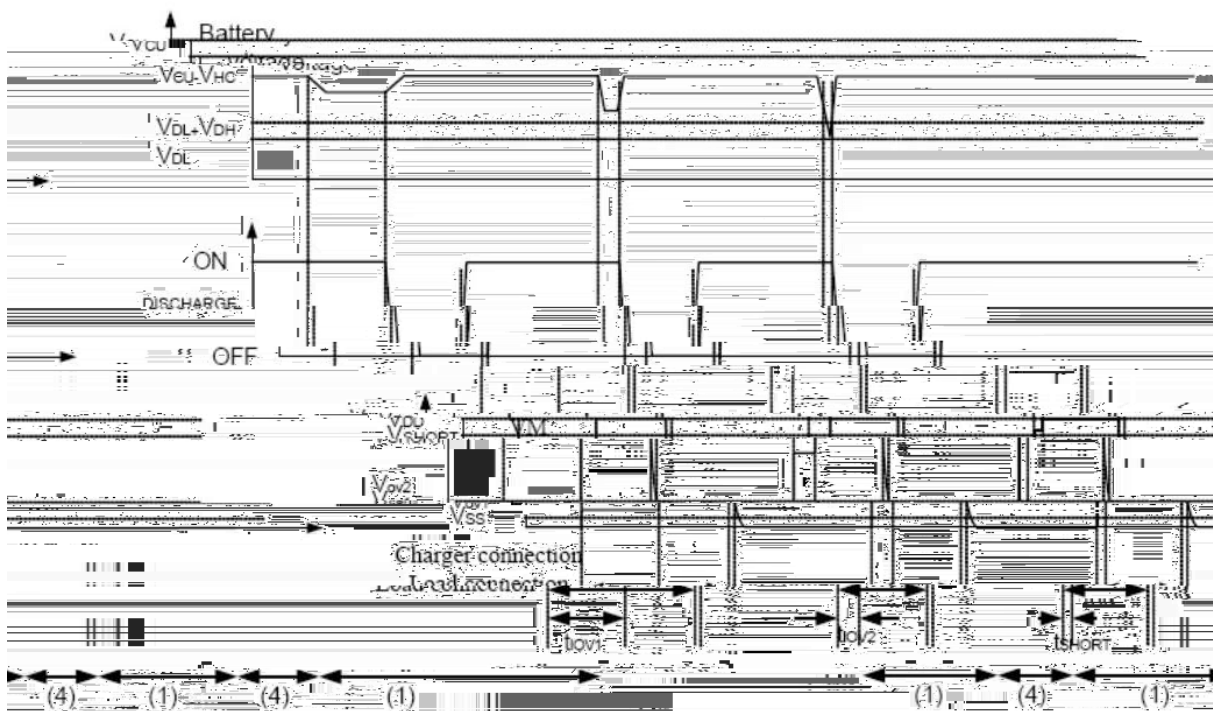
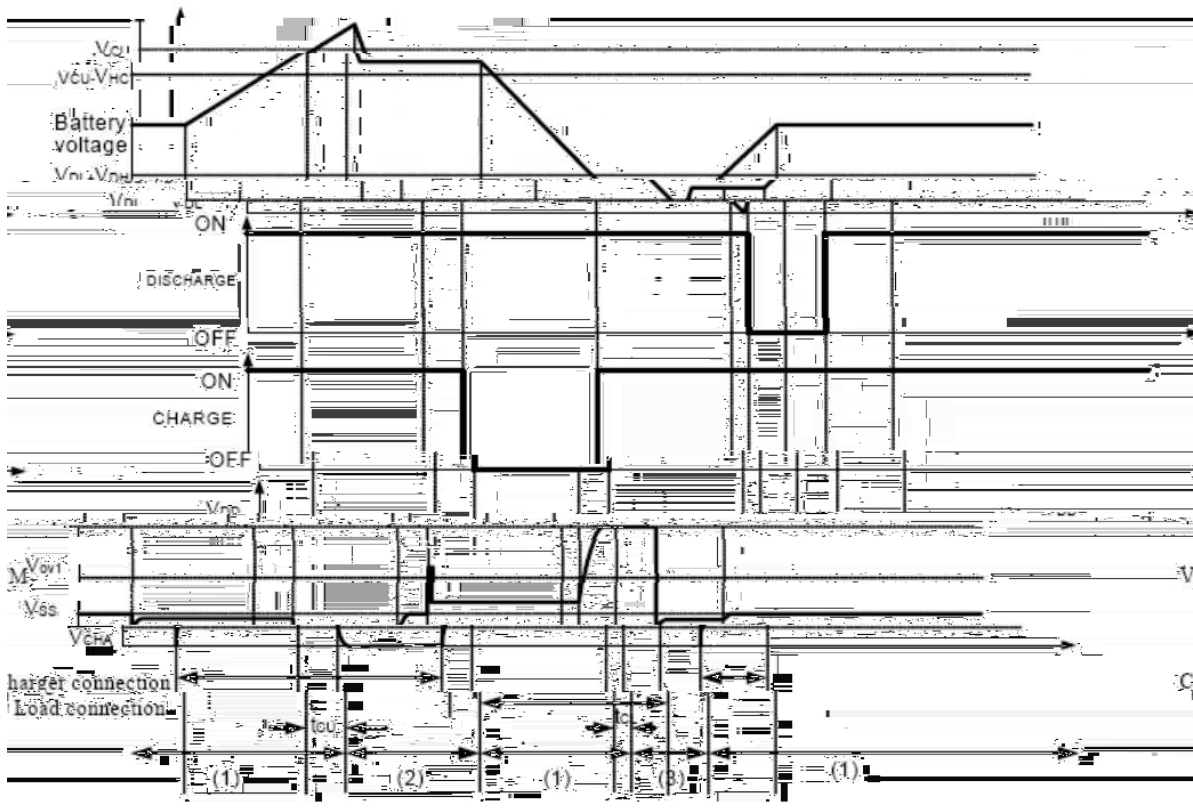
TDL BRCL3120SE VDL ,
 FET VM VDD RVMD
 IPDN VM VCHA VM
 VDD RVMD (VDL)
 BRCL3120SE FET FET
 VM VCHA ,
 VDR

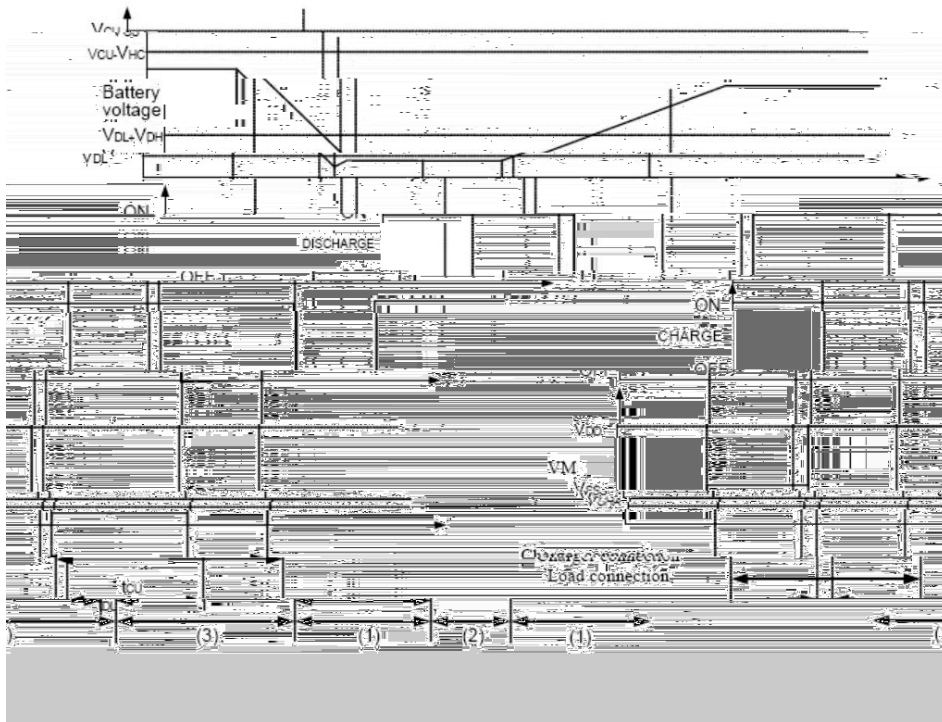
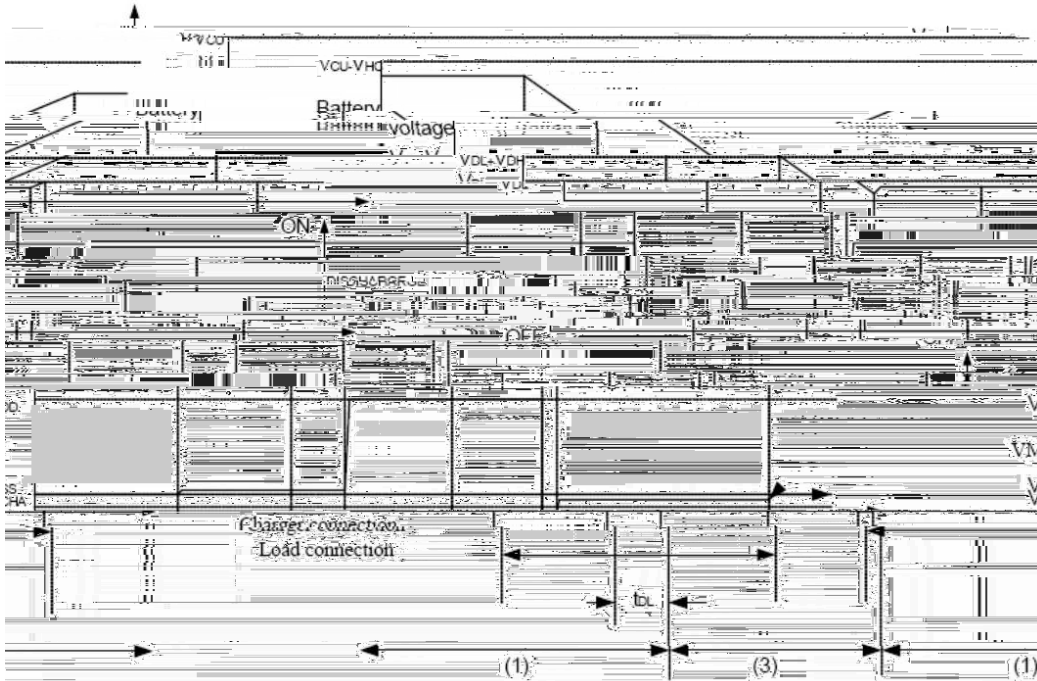
VM
 ,BRCL3120SE FET
 1 2 VM GND RVMS
 VM GND VM VDD
 VM RVMS VM VM
 1

VM (VCHA)
 BRCL3120SE FET
 VM GND (VCHA)
 OV OV

VM V_{SHORT} t_{SHORT}
 BRCL3120SE VM VSHORT

OV
 OV
 1. VDL IC
 " OV " " OV "
 2. " OV " " " OV
 " IC " VDL
 3. VM GND VM GND





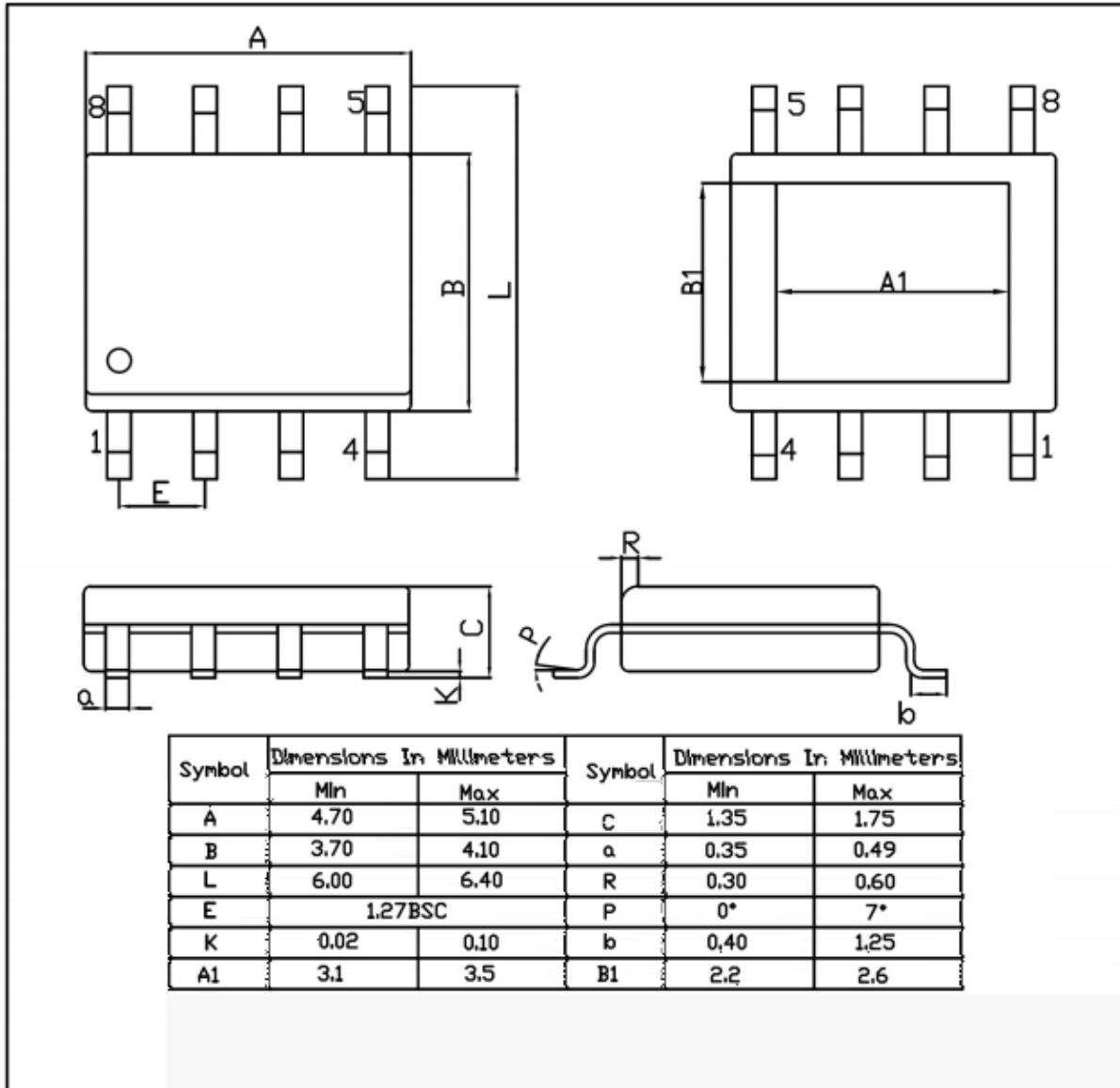
1 2 3 4



/ Package Dimensions

ESOP-8

Unit:mm





/ Marking Instructions



BR:

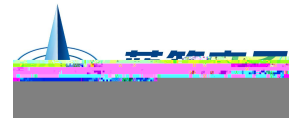
3120

Note:

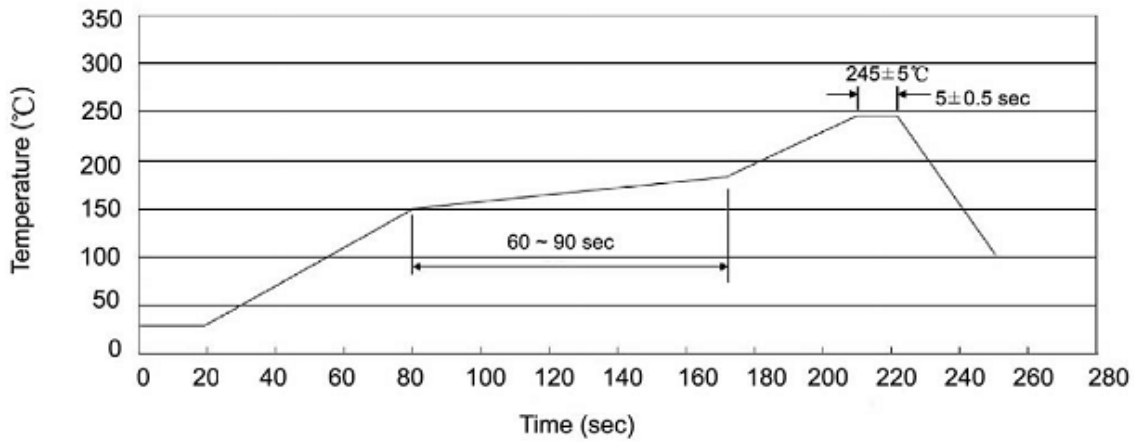
BR: Company Code

3120: Product Type.

****: Lot No. Code, code change with Lot No.



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|---------|-----|---------|----------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1. Preheating: 150~180 , Time: 60~90sec. |
| 2 | 245 ± 5 | | 5 ± 0.5 | sec; | 2. Peak Temp.: 245 ± 5 , Duration: 5 ± 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260 ± 5 10 ± 1 sec. Temp.: 260 ± 5 Time: 10 ± 1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ESOP-8	4,000	2	8,000	6	48,000	13" × 12	360×360×50	385×257×392

/ Notices